

## **Application Data Sheet**

### **Application Information**

Application Type::	Regular
Subject Matter::	Utility
Suggested Group Art Unit::	N/A
CD-ROM or CD-R?::	None
Sequence submission?::	None
Computer Readable Form (CRF)?::	No
Title::	BACKSIDE OF CHIP IMPLEMENTATION OF REDUNDANCY FUSES AND CONTACT PADS
Attorney Docket Number::	INTECH 3.0-085
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	2
Total Drawing Sheets::	2
Small Entity?::	No
Petition included?::	No
Secrecy Order in Parent Appl.?::	No

### **Applicant Information**

Applicant Authority Type::	Inventor
Primary Citizenship Country::	Austria
Status::	Full Capacity
Given Name::	Peter
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City of Residence::	Unterhaching
Country of Residence::	Germany
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City of mailing address::	Unterhaching
Country of mailing address::	Germany

Postal or Zip Code of mailing address:: D-82008

**Correspondence Information**

Correspondence Customer Number:: 000530

**Representative Information**

Representative Customer Number:: 000530

**Assignee Information**

Assignee name:: Infineon Technologies North America Corp.

Street of mailing address:: 1730 North First Street

City of mailing address:: San Jose

State or Province of mailing address:: CA

Postal or Zip Code of mailing address:: 95112